PATENT ASSIGNMENT COVER SHEET

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Stylesheet Version v1.2

EPAS ID: PAT7107948

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
MASAYUKI ARAKAWA	11/17/2021
JUNPEI HOKARI	11/16/2021
AKIRA KOJIMA	12/06/2021
MASAKI MIZUOCHI	11/16/2021
TOMOKAZU KOBAYASHI	12/06/2021
TAKAAKI KIKUCHI	12/07/2021

RECEIVING PARTY DATA

Name:	HITACHI HIGH-TECH CORPORATION
Street Address:	17-1, TORANOMON 1-CHOME
City:	MINATO-KU, TOKYO
State/Country:	JAPAN

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	29789677

CORRESPONDENCE DATA

Fax Number: (202)628-8884

Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.

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Email: edocket@crowell.com, Rfleming@crowell.com
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Address Line 1: P.O. BOX 14300
Address Line 4: WASHINGTON, D.C. 20044-4300

ATTORNEY DOCKET NUMBER:	100929.DA776US
NAME OF SUBMITTER:	LISA A. ADELSON
SIGNATURE:	/Lisa A. Adelson/
DATE SIGNED:	01/06/2022

Total Attachments: 12
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ASSIGNMENT
（譲渡証）

As a below named inventor, I hereby declare that:

IN CONSIDERATION of the sum of One Dollar ($1.00) or the equivalent thereof, and other good and valuable consideration paid to me, by **Hitachi High-Tech Corporation**, a corporation organized under the laws of **Japan**, located at **17-1, Toranomon 1-chome, Minato-ku, Tokyo, Japan**, receipt of which is hereby acknowledged, I do hereby sell and assign to said **Hitachi High-Tech Corporation**, its successors and assigns, all my right, title and interest, in and for the United States of America, in and to

APPARATUS FOR EVALUATING SEMICONDUCTOR SUBSTRATE

invented by me (if only one is named below) or us (if plural inventors are named below) and described in the application for United States Letters Patent therefor, Serial No. **29/789,677**, filed on **October 13, 2021**, executed on even date herewith, and all United States Letters Patent which may be granted therefor, and all divisions, continuations and extensions thereof, the said interest being the entire ownership of the said Letters Patent when granted, to be held and enjoyed by said **Hitachi High-Tech Corporation**, its successors, assigns or other legal representatives, to the full end of term for which said Letters Patent may be granted, as fully and entirely as the same would have been held and enjoyed by me or us if this assignment and sale had not been made;

And I hereby agree to sign and execute any further documents or instruments which may be necessary, lawful, and proper in the prosecution of the above-named application or in the preparation and prosecution of any continuing, continuation-in-part, substitute, divisional, renewal, reviewed or reissue applications or in any amendment, extension, or interference proceedings, or otherwise to secure the title thereto in said assignee;

And I do hereby authorize and request the Commissioner of Patents to issue said Letters Patent to said **Hitachi High-Tech Corporation.**

Signed on the date(s) indicated aside signatures:

INVENTOR(S) （発明者フルネームサイン）	Date Signed （署名日）
1) /Masayuki Arakawa/ **Masayuki ARAKAWA**	November 17, 2021
2) **Junpei HOKARI**	

INVENTOR(S) （発明者フルネームサイン）	Date Signed （署名日）
3) ______________________ **Akira KOJIMA**	______________
4) ______________________ **Masaki MIZUOCHI**	______________
5) ______________________ **Tomokazu KOBAYASHI**	______________
6) ______________________ **Takaaki KIKUCHI**	______________

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INVENTOR(S) （発明者フルネームサイン）	Date Signed （署名日）
1) ____________________ **Masayuki ARAKAWA**	____________________
2) /Junpei Hokari/ **Junpei HOKARI**	November 16, 2021

INVENTOR(S) （発明者フルネームサイン）	Date Signed （署名日）
3) ____________________ **Akira KOJIMA**	____________________
4) ____________________ **Masaki MIZUOCHI**	____________________
5) ____________________ **Tomokazu KOBAYASHI**	____________________
6) ____________________ **Takaaki KIKUCHI**	____________________

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2) ______________________ **Junpei HOKARI**	______________

INVENTOR(S) （発明者フルネームサイン）	Date Signed （署名日）
3) /Akira Kojima/ **Akira KOJIMA**	December 6,2021
4) **Masaki MIZUOCHI**	
5) **Tomokazu KOBAYASHI**	
6) **Takaaki KIKUCHI**	

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2) ____________________ **Junpei HOKARI**	____________________

INVENTOR(S) （発明者フルネームサイン）	Date Signed （署名日）
3) ______________________ **Akira KOJIMA**	______________________
4) /Masaki Mizuochi/ **Masaki MIZUOCHI**	November 16, 2021
5) ______________________ **Tomokazu KOBAYASHI**	______________________
6) ______________________ **Takaaki KIKUCHI**	______________________

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3) ______________________ **Akira KOJIMA**	______________________
4) ______________________ **Masaki MIZUOCHI**	______________________
5) /Tomokazu Kobayashi/ **Tomokazu KOBAYASHI**	December 06 ,2021
6) ______________________ **Takaaki KIKUCHI**	______________________

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4) ______________________ **Masaki MIZUOCHI**	______________
5) ______________________ **Tomokazu KOBAYASHI**	______________
6) /Takaaki KIKUCHI/ **Takaaki KIKUCHI**	December 7,2021